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January 13, 2004

To: Commissioner for Patents

P.O.Box 1450

Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/697,746 10/30/03

Tze Ho Chan et al.

METHOD TO SELECTIVELY FORM POLY SIGE P TYPE ELECTRODE AND POLY-SILICON N TYPE ELECTRODE THROUGH PLANARIZATION

## INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to comply with the duty of disclosure under CFR 1.97-1.99 and 37 CFR 1.56.

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

CS-01-193

The following three U.S. Patents disclose dual gate oxide processes:

- 1) U.S. Patent 6,358,819 to Shelton et al., "Dual Gate Oxide Process for Deep Submicron ICs."
- 2) U.S. Patent 5,918,116 to Chittipeddi, "Process for Forming Gate Oxides Possessing Different Thicknesses on a Semiconductor Substrate."
- 3) U.S. Patent 6,063,670 to Lin et al., "Gate Fabrication Processes for Split-Gate Transistors."
- U.S. Patent 6,342,438 to Yu et al., "Method of Manufacturing a Dual Doped CMOS Gate," teaches doping PMOS and NMOS regions differently before patterning polysilicon gates.
- U.S. Patent 5,356,821 to Naruse et al., "Method for Manufacturing Semiconductor Integrated Circuit Device," discloses epitaxial growth of SiGe gates for both NMOS and PMOS.
- U.S. Patent 6,376,323 to Kim et al., "Fabrication of Gate of P-Channel Field Effect Transistor with Added Implantation Before Pattering of the Gate," teaches PolySiGe gates for both PMOS and NMOS with selective doping.

CS-01-193

CS-01-093 serial number 10/266,425, filed 10/08/02, to Chew-Hoe Ang et al., "Dual Si-Ge Polysilicon Gate with Different Ge Concentrations for CMOS Device Optimization," discloses a method for forming SiGe gates having different Ge concentrations for PMOS and NMOS.

Sincerely

Stephen B. Ackerman, Reg. No. 37761

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.